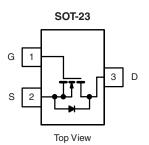


ACE2302BBM+H N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^e	Q _g (Typ.)			
	0.028 at V _{GS} = 4.5 V	6 ^a				
20	0.042 at V _{GS} = 2.5 V	6 ^a	8.8 nC			
	0.050 at V _{GS} = 1.8 V	5.6				



FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_q Tested
- Compliant to RoHS Directive 2002/95/EC



ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- DC/DC Converters
- Load Switch for Portable Applications

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage		V_{DS}	20	V		
Gate-Source Voltage		V_{GS}	± 12	\		
	T _C = 25 °C		6 ^a			
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 70 °C	1 , [5.1]		
Continuous Diain Current (1, = 150°C)	T _A = 25 °C	- I _D	5 ^{b, c}	А		
	T _A = 70 °C		4 ^{b, c}			
Pulsed Drain Current		I _{DM}	20	1		
Continuous Source-Drain Diode Current	T _C = 25 °C		1.75			
Continuous Source-Diam Diode Current	T _A = 25 °C	l _S	1.04 ^{b, c}	1		
	T _C = 25 °C		2.1			
Maximum Power Dissipation	T _C = 70 °C	1 5	1.3	w		
Maximum Fower Dissipation	T _A = 25 °C	- P _D	1.25 ^{b, c}	- vv		
	T _A = 70 °C	1	0.8 ^{b, c}			
Operating Junction and Storage Temperature	e Range	T _J , T _{stg}	- 55 to 150	°C		
Soldering Recommendations (Peak Tempera	ature)		260			

THERMAL RESISTANCE RATINGS								
Parameter	Symbol	Typical	Maximum	Unit				
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	80	100	°C/W			
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	40	60	7 5/1			

Notes:

- a. Package limited
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 125 $^{\circ}\text{C/W}.$
- e. Based on T_C = 25 °C.

服务热线:400-655-8788

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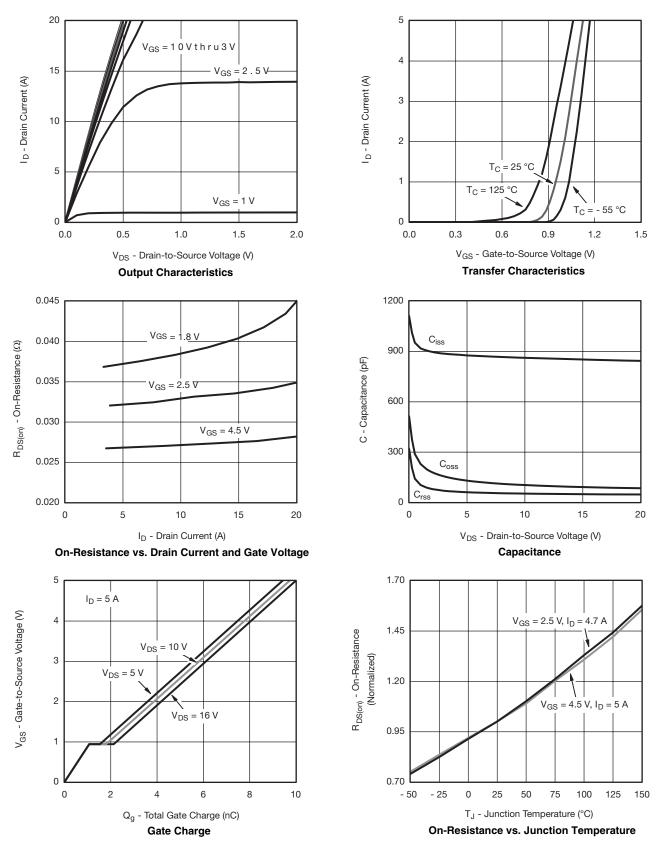
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	<u> </u>		,			
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	T _J I _D = 250 μA		25		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 2.6		mv/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	0.45		1.0	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA
	I _{DSS}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$			1	
Zero Gate Voltage Drain Current		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 70 \text{ °C}$			10	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	20			Α
	. ,	$V_{GS} = 4.5 \text{ V}, I_D = 5.0 \text{ A}$		0.028	+ +	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 2.5 \text{ V}, I_D = 4.7 \text{ A}$		0.042		Ω
	\ \ \ \	$V_{GS} = 1.8 \text{ V}, I_D = 4.3 \text{ A}$		0.050	 	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 5.0 A		24		S
Dynamic ^b		-		l	l	
Input Capacitance	C _{iss}			865		pF
Output Capacitance	C _{oss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		105		
Reverse Transfer Capacitance	C _{rss}			55		
Tievelse Transfer Capacitaries		V _{DS} = 10 V, V _{GS} = 5 V, I _D = 5.0 A		12	18	1
Total Gate Charge	Qg	20 / 00 / 2		8.8	14	nC
Gate-Source Charge	Q _{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 5.0 \text{ A}$		1.1		
Gate-Drain Charge	Q _{gd}	ge v de v g		0.7		
Gate Resistance	R _g	f = 1 MHz	0.5	2.4	4.8	Ω
Turn-On Delay Time	t _{d(on)}			8	16	
Rise Time	t _r	V_{DD} = 10 V, R_L = 2.2 Ω		17	26	
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong \text{4 A, V}_\text{GEN}=\text{4.5 V, R}_g=\text{1}~\Omega$		31	47	
Fall Time	t _f			8	16	
Turn-On Delay Time	t _{d(on)}			5	10	ns
Rise Time	t _r	V_{DD} = 10 V, R_L = 2.2 Ω		13	20	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 4$ A, $V_{GEN}=5$ V, $R_g=1$ Ω		21	32	
Fall Time	t _f			6	12	-
Drain-Source Body Diode Characteristic	-		<u> </u>	<u> </u>		
Continuous Source-Drain Diode Current	Is	T _C = 25 °C			1.75	
Pulse Diode Forward Current	I _{SM}	-			20	A
Body Diode Voltage	V _{SD}	I _S = 4 A, V _{GS} = 0 V		0.75	1.2	V
Body Diode Reverse Recovery Time	t _{rr}	- 40		12	20	ns
Body Diode Reverse Recovery Charge	Q _{rr}			5	10	nC
Reverse Recovery Fall Time	t _a	a		7		
Reverse Recovery Rise Time	t _b			5		ns

Notes:

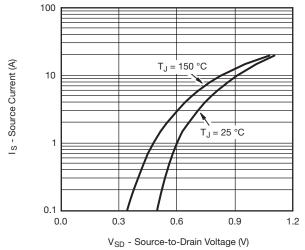
- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 % b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

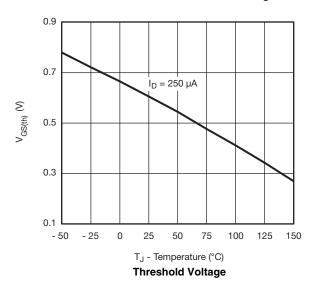








Source-Drain Diode Forward Voltage

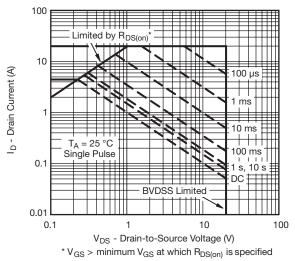


 $I_D = 5 \text{ A}$ $I_D = 6 \text{ A}$ I_D

On-Resistance vs. Gate-to-Source Voltage

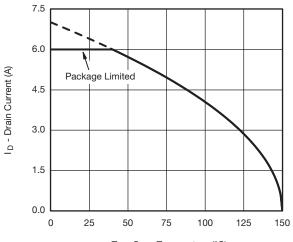


Single Pulse Power (Junction-to-Ambient)



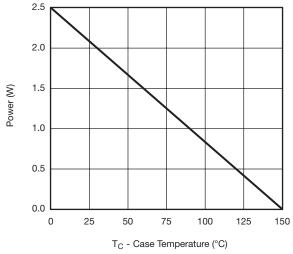
Safe Operating Area, Junction-to-Ambient

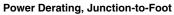


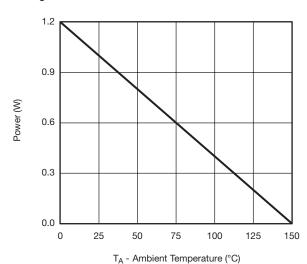


T_C - Case Temperature (°C)

Current Derating*



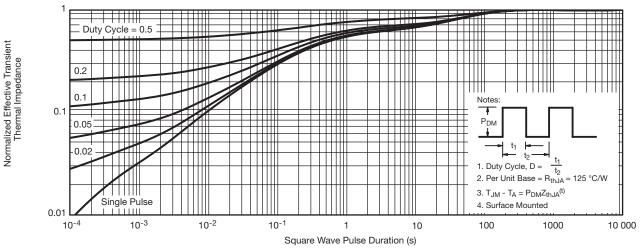




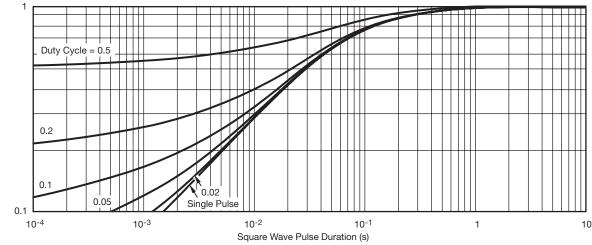
Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient

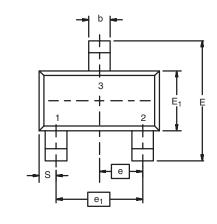


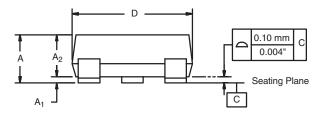
Normalized Thermal Transient Impedance, Junction-to-Foot

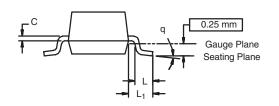
Normalized Effective Transient Thermal Impedance



SOT-23 (TO-236): 3-LEAD







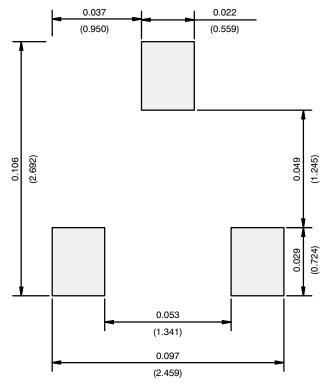
Dim	MILLI	METERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.9	BSC 0.0374		4 Ref	
e ₁	1.9	0 BSC	0.074	8 Ref	
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
FCN: S-03946-Rev K 09-	Jul-01	•			

ECN: S-03946-Rev. K, 09-Jul-01

DWG: 5479



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)



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